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**High Thermal Conductivity** 

Stress Free Solvent Free Reworkable Epoxy Paste Adhesive

**IDEAL FOR:** 

High Power Die Attach Substrate and Component Reworkability Mismatched CTE's

#### **DESCRIPTION:**

ME7155-AN is a reworkable, aluminum nitride filled, electrically insulating and thermally conductive epoxy paste adhesive which exhibits outstanding flexibility for bonding materials having highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper). The high thermal conductivity of this material makes it useful for bonding high-powered, large area die and components.

It can be readily reworked at 80-100°C.

## **AVAILABILITY:**

ME7155-AN is available in syringes for automatic needle dispense applications or in jars.

### **APPLICATION PROCEDURES:**

- (1) Thaw for 30 minutes at ambient temperature in the original container.
- (2) Dispense adhesive onto clean substrate.
- (3) Cure according to one of the recommended schedules.

# PRIMA-BOND ME7155-AN

### **TYPICAL PROPERTIES\***

Electrical Resistivity >1x10<sup>14</sup> ohm-cm ( 150 °C/ 60 minute )

Dielectric Strength (Volts/mil) >750
Glass Transition Temp.(°C) -25 ±10%
Current Carrying Capabilities N/A
Lap-Shear Strength >900 psi

>6.2 N/mm<sup>2</sup>

Device Push-off Strength >1800 psi

>12.4 N/mm<sup>2</sup>

Hardness (Type) 80 (A)  $\pm 10\%$ Cured Density (gm/cc) 2.3  $\pm 10\%$ 

Thermal Conductivity 25 Btu-in/hr-ft<sup>2</sup>-°F ±10%

3.6 W/m-°C ±10%

Linear Thermal Expansion 120 ±15%

Coeff. (ppm/°C)

Maximum Continuous Operation Temp. (°C) <150

Avg. Viscosity(0.5 rpm, 24°C) 240,000 cp ±20%

(Brookfield DV-1,spindle CP51)

### **CURE SCHEDULES:**

<u>Temperature</u>	<u>Time</u>	<u>Presure</u>
80°C	8 hr	
100°C	4 hr	
125°C	2 hr	
150°C	1 hr	

### **SHELF LIFE:**

Storage temperature
Shelf Life
-40°C 1 yr

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details

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